

# Dynasolve™ 185



## Amine-cured Epoxy Cleaning Solvent



Dynasolve 185 is a formulated solvent used to remove amine-cured epoxy systems in both electronic and industrial applications. It contains a proprietary blend of ingredients that facilitate polymer removal and prevent the depositing of particles back onto a part.

### CLEANING APPLICATIONS:

Depotting and decapsulating of electronic components  
Industrial epoxy removal and cleaning

### ADVANTAGES:

More efficient than acetone, MEK & other solvents  
Formulated to be highly selective  
No chlorinated, acidic or caustic components  
High resin loading capacity allows for reuse and reduced cost of ownership  
High flash point

### SPECIFICATIONS:

|                   |                   |
|-------------------|-------------------|
| Specific gravity: | 1.04              |
| Boiling point:    | > 369°F (> 187°C) |
| Flash point:      | 207°F (97°C)      |

### MATERIALS REMOVED:

Amine-cured epoxy  
Many types of inks  
Acrylic emulsions

### PRODUCT USAGE GUIDELINES

(SEE SDS FOR EH&S INFORMATION)

1. Heat Dynasolve 185 to 200°F (93°C) and immerse part.
2. Observe carefully. If epoxy appears unaffected after 1 hour, increase temperature to 250° – 300°F (121° – 148°C).
3. After successful removal of epoxy, rinse with alcohol or water.
4. If epoxy appears unaffected after 2 hours, call for technical support.

### MATERIAL COMPATIBILITY:

**Recommended materials including:**

All metals  
Teflon®  
Polyethylene & polypropylene

**Avoid materials including:**

Viton®  
PVC  
Acrylic



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